

# DA3X105D

## Silicon epitaxial planar type

For high speed switching circuits  
2 elements anode-common type

### ■ Features

- Short reverse recovery time  $t_{rr}$
- Low terminal capacitance  $C_t$
- Contributes to miniaturization of sets, mount area reduction
- Eco-friendly Halogen-free package

### ■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	80	V
Maximum peak reverse voltage	$V_{RM}$	80	V
Forward current	Single	$I_F$	100
	Double		150
Peak forward current	Single	$I_{FM}$	225
	Double		340
Non-repetitive peak forward surge current *	Single	$I_{FSM}$	500
	Double		750
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

Note) \*:  $1\text{ t} = 1\text{ s}$

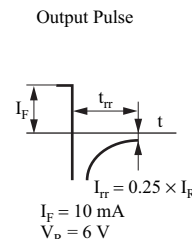
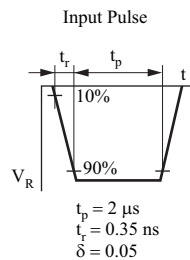
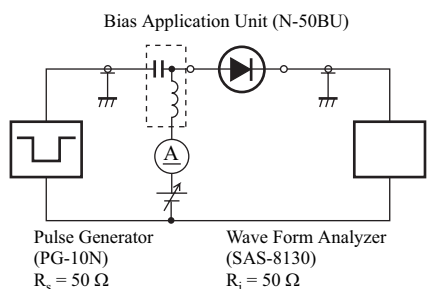
### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 100\text{ mA}$			1.2	V
Reverse voltage	$V_R$	$I_R = 100\ \mu\text{A}$	80			V
Reverse current	$I_R$	$V_R = 80\text{ V}$			100	nA
Terminal capacitance	$C_t$	$V_R = 0\text{ V}, f = 1\text{ MHz}$			15	pF
Reverse recovery time *	$t_{rr}$	$I_F = 10\text{ mA}, V_R = 6\text{ V}, I_{rr} = 0.25 \times I_R$			10	ns
Transistor current	$I_C$	$V_{1-2} = \pm 15\text{ V}, I_3 = 10\text{ mA}$		2	10	$\mu\text{A}$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 100 MHz

3. \*:  $t_{rr}$  measurement circuit

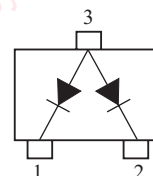


### ■ Package

- Code  
Mini3-G3-B
- Pin Name  
1: Cathode-1                      3: Anode-1  
2: Cathode-2                      Anode-2

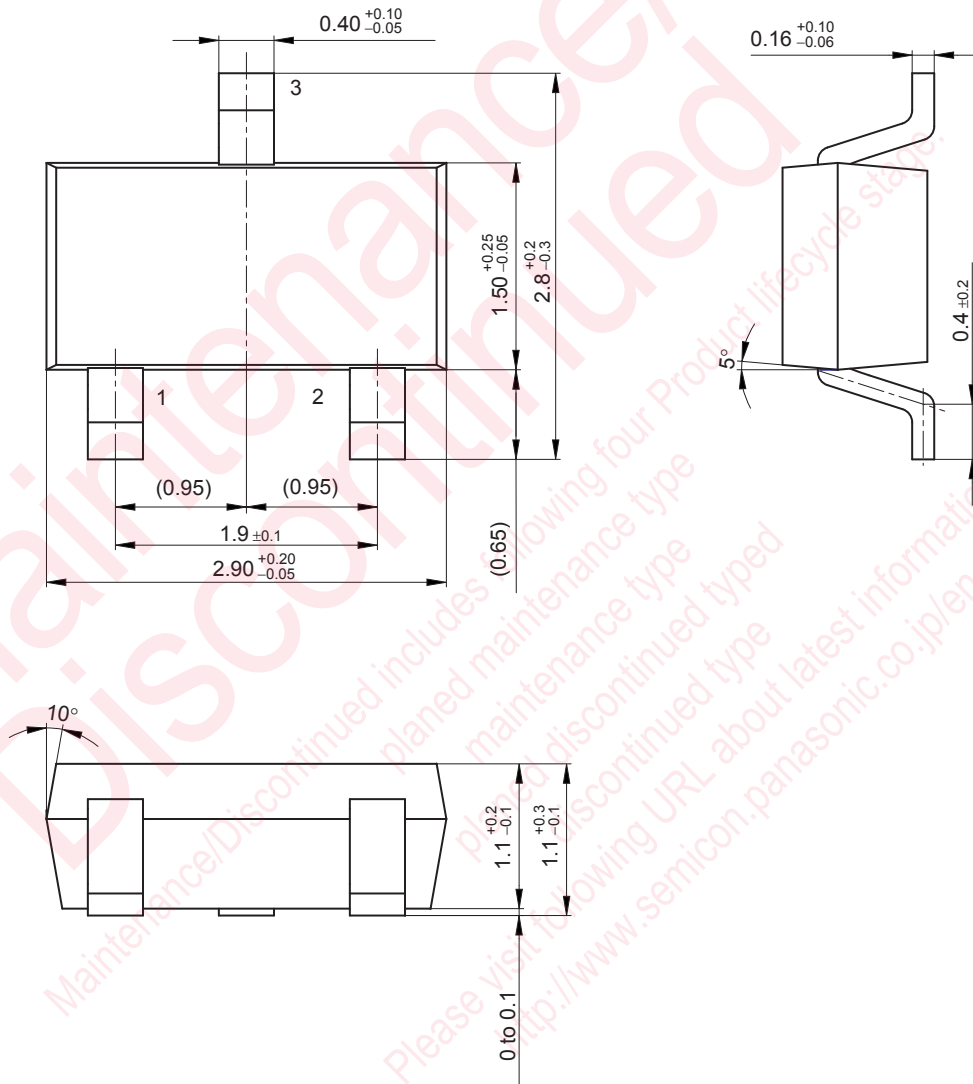
### ■ Marking Symbol: 27

### ■ Internal Connection



Mini3-G3-B

Unit: mm



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